NOTES: (continued)

6. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature numbers SLMA002 (www.ti.com/lit/slm002) and SLMA004 (www.ti.com/lit/slma004).

7. Vias are optional depending on application, refer to device data sheet. It is recommended that vias under paste be filled, plugged or tented.
EXAMPLE STENCIL DESIGN

SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD
64% PRINTED SOLDER COVERAGE BY AREA
SCALE: 7X

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

9. Board assembly site may have different recommendations for stencil design.
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